

ABSTRACT

An integrated circuit (500) includes a semiconductor substrate (400) and an integrated circuit package (530). The semiconductor substrate (400) has a first pair of bonding pads (442, 444) conducting a differential output signal thereon and adapted to be coupled to an input of a first external filter, and a second pair of bonding pads (452, 454) conducting a differential input signal thereon and adapted to be coupled to an output of said first external filter. The integrated circuit package (530) encapsulates the semiconductor substrate (400) and has first (452, 454) and second (552, 554) terminal pairs corresponding and coupled to the first (442, 444) and second (452, 454) pairs of bonding pads, respectively. The first (452, 454) and second (552, 554) terminal pairs are separated by a first predetermined distance is sufficient to maintain an input-to-output isolation therebetween of at least a first predetermined amount.